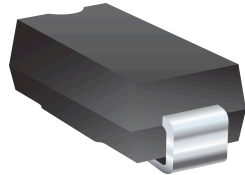


# MATERIAL DECLARATION SHEET



Material Number	TISP4SxxxBJR-S SERIES			
Product Line	Semiconductor Products			
Compliance Date	2012/06/06			
RoHS Compliant	YES	MSL	1	

No.	Construction Element(subpart)	Homogeneous Material	Material weight [g]	Homogeneous Material\ Substances	CASRN if applicable	Materials Mass %	Material Mass % of total unit wt.	Subpart mass of total wt. (%)
1	Outside Lead finish	Matte-100% tin	0.001011	Tin	7440-31-5	100.00	1.093	1.093
2	Molding compound	EME-E210 compound	0.0535	Silica	14808-60-7	76.00	43.951	57.831
				Epoxy resin	25928-94-3	9.00	5.205	
				Phenolic resin-A,B	9003-35-4	8.00	4.626	
				Metal hydroxide	Trade secret	6.00	3.470	
				Carbon black	1333-86-4	1.00	0.578	
3	Lead frame	Copper	0.0335	Copper	7440-50-8	99.80	36.139	36.212
				Iron	7439-89-6	0.15	0.054	
				Phosphorus	7723-14-0	0.05	0.018	
4	Die attach (solder)	Solder paste	0.00215	Tin	7440-31-5	5.00	0.116	2.324
				Lead	7439-92-1	92.50	2.150	
				Silver	7440-22-4	2.50	0.058	
5	Chip	Silicon	0.002348	Silicon	7440-21-3	99.86	2.537	2.541
		Metallization		Nickel	7440-02-0	0.05	0.001	
		Passivation	0.000002	Lead oxide	1317-36-8	0.047	0.001	
				Silicon dioxide	7631-86-9	0.038	0.001	
				Aluminum oxide	1344-28-1	0.004	0.0001	
		Total weight	0.092511					

This Document was updated on: 2012/06/06

**Important remarks:**

1. It is the responsibility of the user to verify they are accessing the latest version.